

WHAT IS CLAIMED IS:

- D-1A*
1. A heat-sensitive stencil comprising a porous resin layer and a resin film laminated on said porous resin layer, and a thin resin layer interposed between said porous resin layer and said porous resin layer.
2. A heat-sensitive stencil as set forth in claim 1, wherein said resin film is thermoplastic.
- 10 3. A heat-sensitive stencil as set forth in claim 1, wherein said thin resin layer has at least one resin component which is the same as that of said porous resin layer.
- 15 4. A heat-sensitive stencil as set forth in claim 1, wherein said thin resin layer has no resin component which is common to that of said porous resin layer.
- 20 5. A heat-sensitive stencil as set forth in claim 1, wherein said thin resin layer and said porous resin layer form a continuous unitary body.
- 25 6. A heat-sensitive stencil as set forth in claim 1, further comprising a non-resinous porous layer formed on said porous resin layer.
- 30 7. A heat-sensitive stencil as set forth in claim 1, and having a flexural rigidity of 20-40 mN.
8. A heat-sensitive stencil as set forth in claim 1, and wound around a cylindrical core.
- 35 9. A heat-sensitive stencil as set forth in claim 1, and provided with imagewise perforations.

10. A heat-sensitive stencil as set forth in claim 1,
and providing air permeability of $2.0 \text{ cm}^3/\text{cm}^2 \cdot \text{sec}$ to 160
 $\text{cm}^3/\text{cm}^2 \cdot \text{sec}$, when perforated to have an open ratio of at
5 least 20 %.

11. A heat-sensitive stencil as set forth in claim 1,
wherein said perforations are thermally formed.

10 12. A stencil printer having a stencil as set forth in
claim 9.

13. A method of preparing a heat-sensitive stencil as
set forth in claim 5, comprising the steps of:

15 applying a coating composition to a surface of a
resin film, said composition containing a resin, a first
solvent capable of dissolving said resin, and a second
solvent substantially incapable of dissolving said resin;
and

20 drying said applied composition to form said thin
resin layer and said porous layer on said surface of said
film.

14. A method as set forth in claim 5, wherein the weight
25 ratio of said first resin to said second resin is greater
than 1:1.

15. A method of preparing a heat-sensitive stencil as
set forth in claim 1, comprising the steps of:

30 applying a first coating composition to a surface of
a resin film,

drying said applied first composition to form said
thin resin layer on said surface of said film,

35 applying a second coating composition to a surface
of said thin resin layer, and

~~drying said applied second composition to form said porous resin layer on said surface of said thin resin layer.~~

5 16. A material for forming a stencil, comprising a thin resin layer, and a porous resin layer formed on said resin layer.

10 17. A heat-sensitive stencil comprising a resin film having provided thereon a material according to claim 16.

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